



> VARIOUS LOADING AND UNLOADING CONFIGURATIONS

- > loading: tube, bowl, tray
- > unloading: tube, bulk or metal mag
- > in any combination
- > partner solutions: loading from wafer ring, unloading into tape-and-reel

> INCARRIER FOR MEMS DEVICES

The InMEMS concept combines dedicated MEMS modules with the Multitest InStrip®. This expands the advantages of strip test to MEMS:

Multitest InCarrier® also leverages these benefits for singulated devices.



> FOR MORE INFORMATION

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InCarrier®

- visit www.multitest.com/InCarrier

- or see us at the shows
(more information about Multitest at the trade shows:
www.multitest.com/shows)

**Strip-like Test for
Singulated Packages**

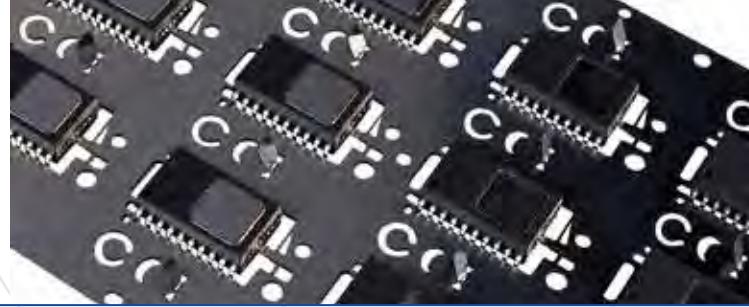
>> www.multitest.com



Combines the advantages of strip and package test

InCarrier®

strip-like test for singulated packages



> COMBINES THE ADVANTAGES OF STRIP AND PACKAGE TEST

The Multitest InCarrier® combines the substantial advantages of the strip handling process with the advantages of the standard test handling process. Thus, it overcomes the constraints of the strip test and even leverages additional advantages.

> STABLE AND HIGH PARALLEL HANDLING SOLUTION FOR THE SMALLEST DEVICES

The InCarrier® provides robust test handling with unprecedented jam rates for the smallest packages. Using the InStrip® test handling platform the InCarrier® supports high parallel multisite test.

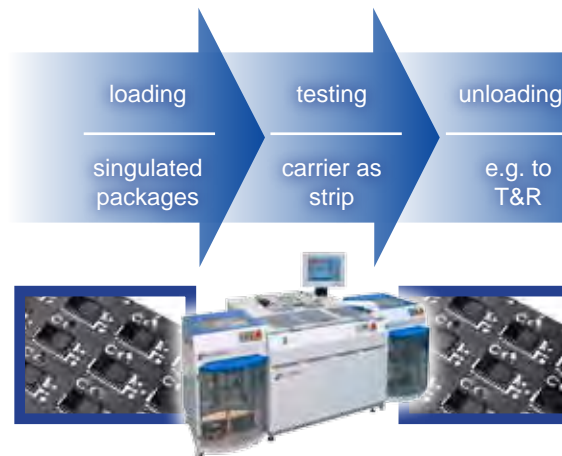
> A SOLUTION FOR VARIOUS APPLICATIONS OF IC AND SENSOR TEST

Multitest is providing so called InMEMS test modules for sensor test and calibration. The InCarrier® supports test on the InStrip®/ InMEMS platform not only for ICs but also for sensors.

> THE INCARRIER® PROCESS

The concept of the InCarrier® consists of a tray/carrier, into which singulated ICs are loaded to be tested in the InStrip®, Multitest's high parallel strip test handler. Finally the tested ICs are unloaded into the final packaging and shipping medium. Multitest offers the InCarrier® Loader/Unloader tool for these processes.

This way the InCarrier® test floor material flow remains over all similar to the established standard process but leverages the multisite capability of the InStrip handler.



> STRIP-LIKE HANDLING SOLUTION

- > high parallel / multisite test
- > stable and robust handling of the smallest packages

> ADVANTAGES OF PACKAGE TEST

InCarrier® helps to fulfil special quality requirements that are only achievable with the single device test:

- > no singulation after test
- > full device traceability
- > re-test option on the same equipment

> MORE ADVANTAGES OF THE INCARRIER®

- > Burn-In Option – use the InCarrier® tray for the burn-in process
- > Kit-less handler the standardized InCarrier trays reduce the package related toolings of the InStrip® handler to the contact unit
- > Independence from suppliers leadframe layout: The InCarrier® is more flexible to adjust the device pitch of the matrix for the InStrip® handler.